

Ceviconn

Manufacturer/Brand : UDE

UDE P/N : RM3-118A9V1F
(Replaced by RM3-118A9V1Q)

UDE P/N : RM3-118A9V1Q

Description : RJ45 multiport 2X1
Through Hole
10/100/1000 Base-T
Contact Area : 30 μ " Gold
LED:L-Green;R-Yellow



Spec No.
RM3327-00

Update Date
2012/10/31

Approved	Checked	Prepared

Contact us :

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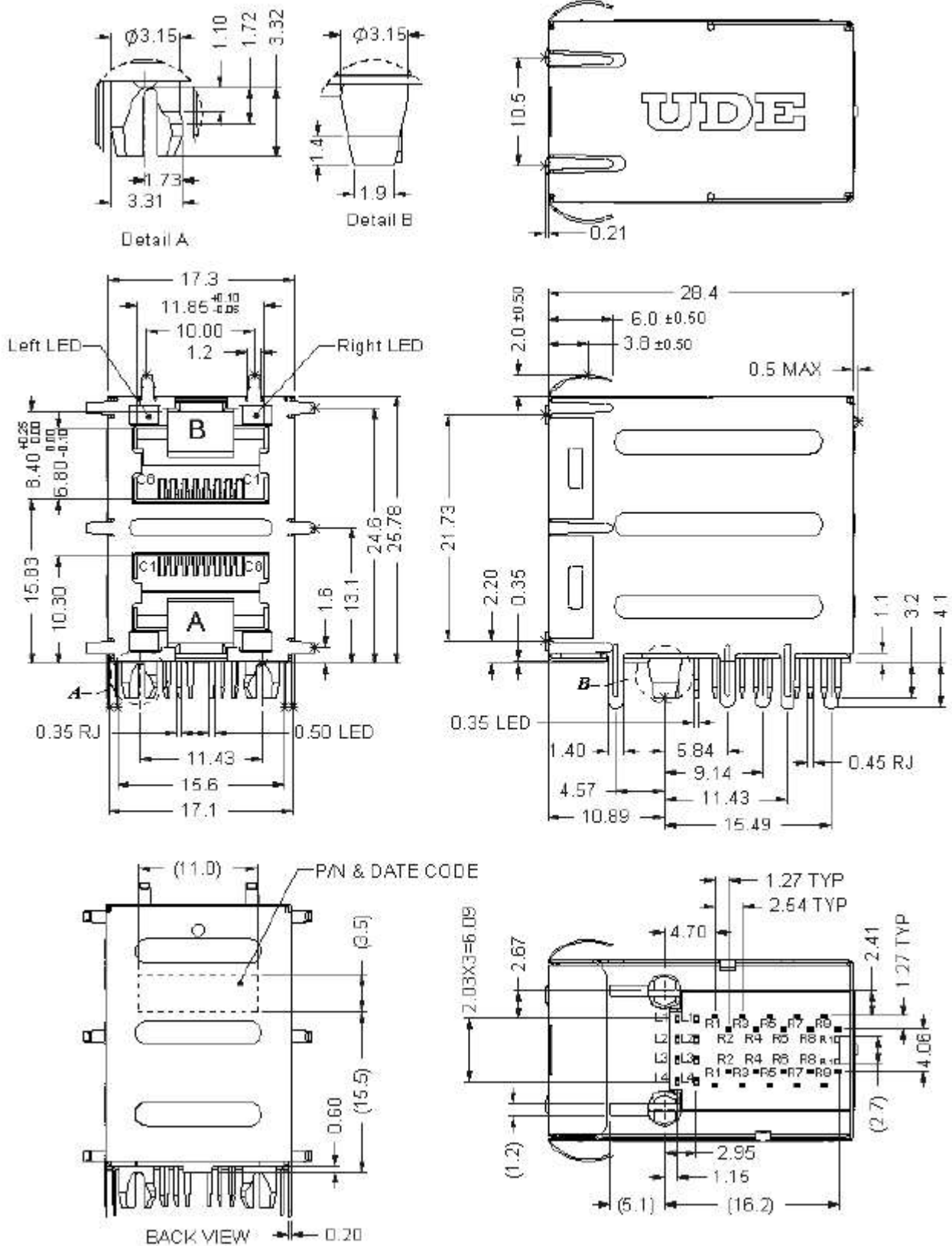
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1. MECHANICAL DIMENSION

1.1 Product Dimension

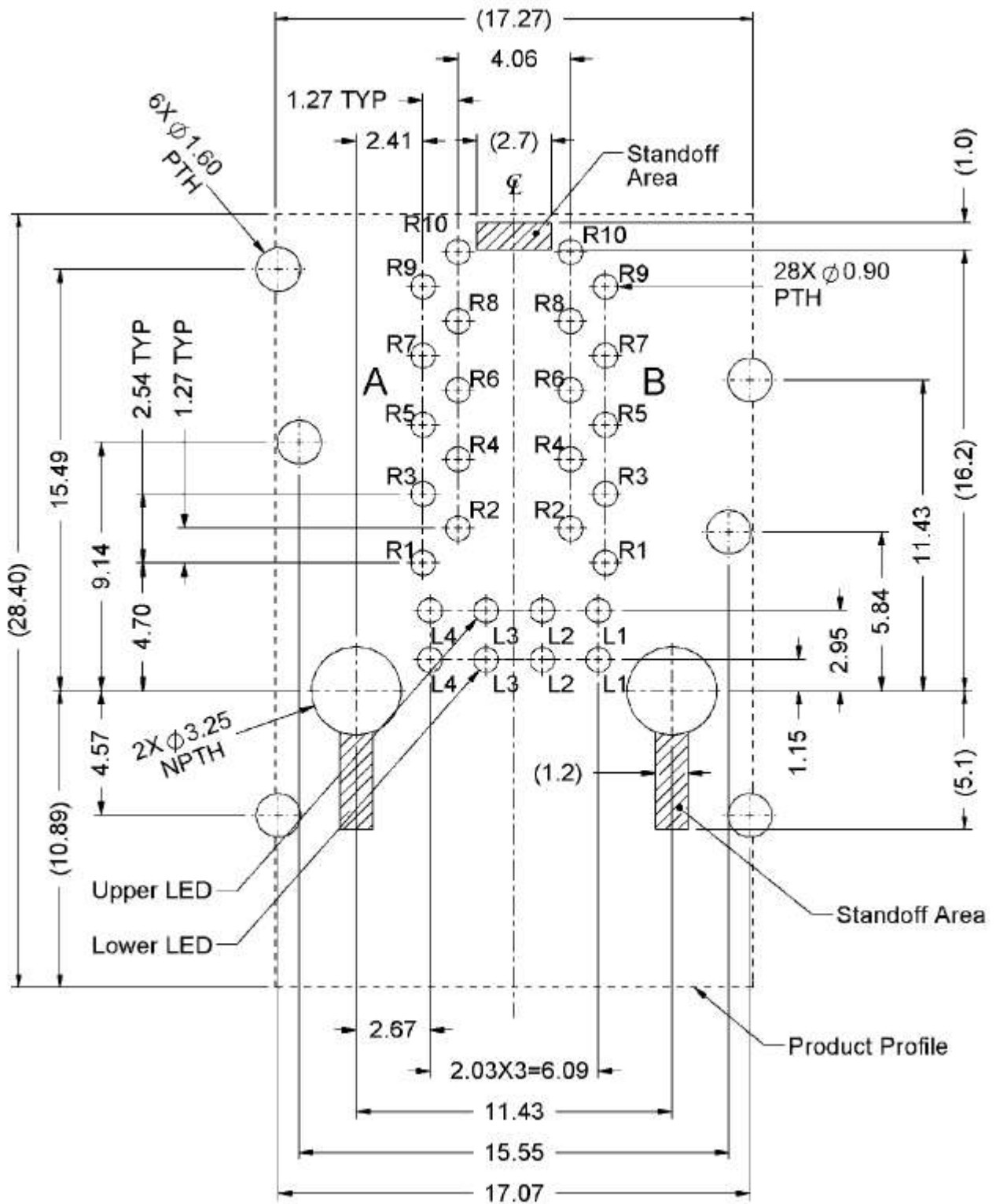
General Tolerance : X.X : ± 0.38
X.XX : ± 0.25



1.2 Recommended PCB Layout

Component Side of Board

All dimension tolerance are $\pm 0.05\text{mm}$ unless otherwise specified



2. REQUIREMENTS

2.1 Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

2.2 Material

2.2.1 Terminal Parts (Underplating : 30 μ " min. Nickel overall)

2.2.1.1 RJ Terminal : YCUT-FX-H, Thickness=0.30mm

Finish : Contact Area : 30 μ " Gold

2.2.1.2 Input Terminal : Brass, Thickness=0.35mm

Finish : 100 μ " min. Tin

2.2.1.3 Case Terminal : Brass, Thickness=0.30mm

Finish : 100 μ " min. Tin

2.2.2 Plastic Parts <UL94V-0>

2.2.2.1 Housing : High Temperature Thermoplastic, Black

2.2.2.2 Case : High Temperature Thermoplastic, Black

2.2.2.3 Spacer : Thermoplastic, Black

2.2.2.4 Terminal Cover : Thermoplastic, Black

2.2.2.5 Terminal Base : Thermoplastic, Black

2.2.2.6 Insert : High Temperature Thermoplastic, Black

2.2.2.7 Light Pipe : PC, Transparent

2.2.3 Shield Parts

2.2.3.1 Front Shield : Stainless, Thickness=0.20mm, unplating

2.2.3.2 Back Shield : Stainless, Thickness=0.20mm, Pre-soldering

2.3 Operating and Storage Temperature

Operating Temperature : 0°C to +70°C

Storage Temperature : -40°C to +85°C

2.4 RJ45 specifications

Insulation Resistance : 500MΩ min.

Insertion force with the latch depressed : 22N max

Removal force with the latch depressed : 44N max

Locking Force of Plug Latch : 50N min. @ 60+/-5 sec

Durability : 2500 cycles

2.5 Performance and Test Description

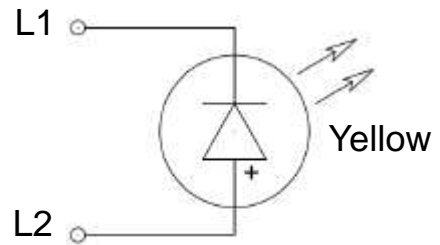
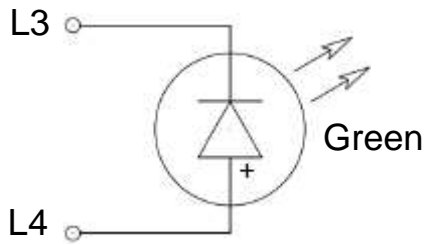
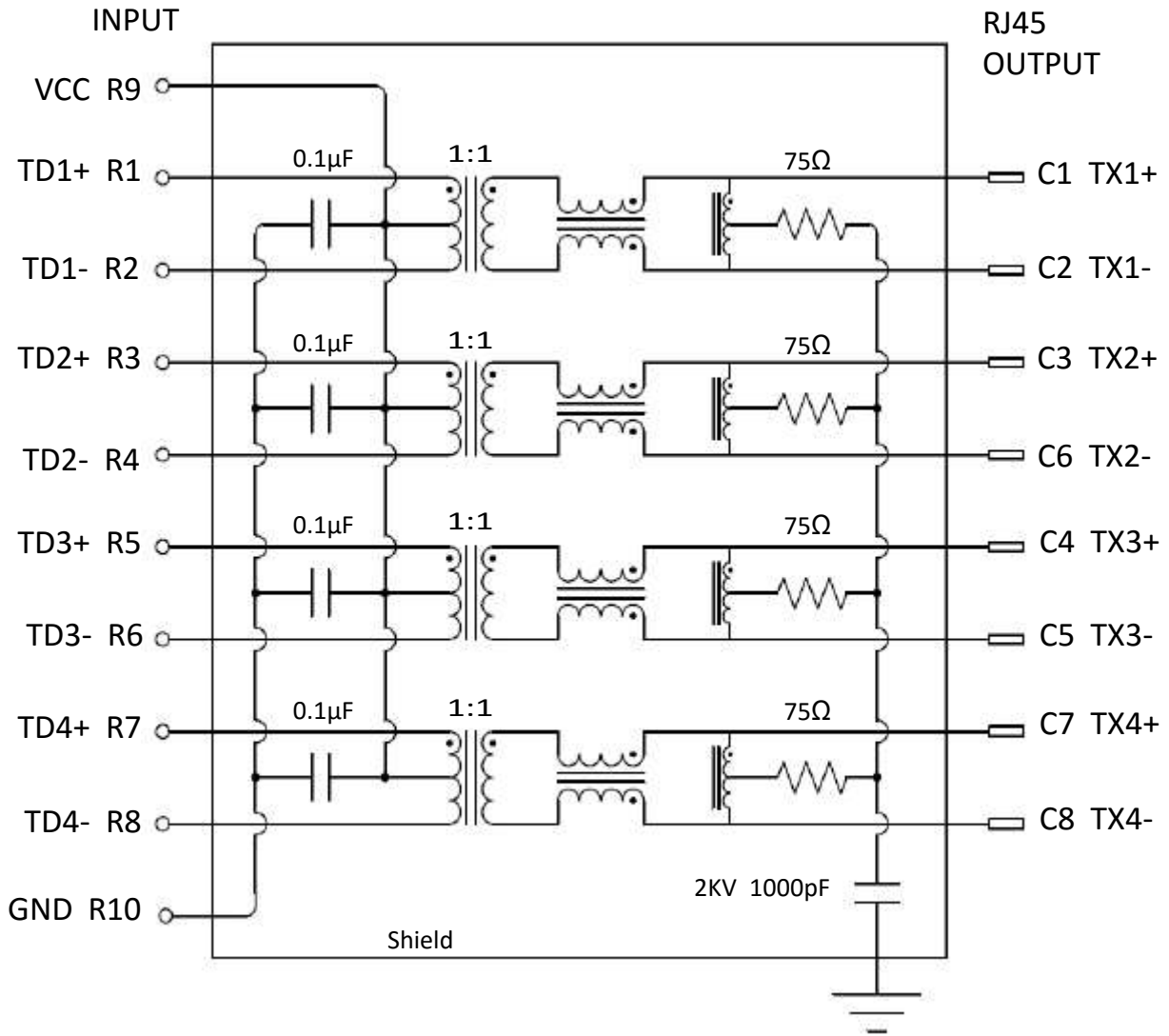
Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table. All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

2.6 Packaging and Packing

All parts shall be packaged and packed to protect against physical damage , corrosion and deterioration during shipment and storage.

3. ELECTRICAL CHARACTERISTICS

3.1 Schematic



Emitting Color	λ_p (nm)	V_f @ $I_f=20mA$	I_r @ $V_r=5V$
Green	565	1.7 ~2.6 V	10 μ A max.
Yellow	585	1.7 ~2.6 V	10 μ A max.

3.2 Transmitter filter & Receiver filter

Type : Balance low pass 100Ω impedance

Insertion loss : 1~100 MHz -1.0dB max.

Return loss : 1~30 MHz -18dB min. load 100Ω

30~60MHz -16dB min. load 100Ω

60~80MHz -12dB min. load 100Ω

80~100MHz -10dB min. load 100Ω

3.3 Common Mode Rejection

@ 1~100 MHz -30dB min.

3.4 Cross Talk

@ 1~100 MHz -30dB min.

3.5 Inductance @ 100KHz, 0.1V, 8mA DC BIAS

Input (R1-R2), Input(R3-R4), Input (R5-R6), Input(R7-R8): 350 μH min.

3.6 HiPot Test

Input(R1-R2) To Output(C1-C2) : 1500Vac 60s or 2250Vdc 60s

Input(R3-R4) To Output(C3-C6) : 1500Vac 60s or 2250Vdc 60s

Input(R5-R6) To Output(C4-C5) : 1500Vac 60s or 2250Vdc 60s

Input(R7-R8) To Output(C7-C8) : 1500Vac 60s or 2250Vdc 60s

4. ORDER INFORMATION

R M 3 - 1 1 8A 9V1 Q
 A B C D

A. LED Code :

L-Green;R-Yellow. <Refer to Schematic of LED>

B. Mechanical Code :

w/ UDE Logo, w/ Top & Side Spring

C. Schematics Code :

9V1 : 9V1 circuit

D. Plating Code :

Underplating	30μ " min. Nickel overall	
Solder Tail	100μ " min. Bright Tin	100μ " min. Matted Tin
Contact Area	A : Gold Flash C : 6μ " gold B : 10μ " gold D : 15μ " gold <u>Q: 30μ " gold</u> G : 50μ " gold	1 : Gold Flash 6 : 6μ " gold 2 : 15μ " gold 3 : 30μ " gold 4 : 50μ " gold

5. DIPPING TEMPERATURE PROFILE

Note :

The measuring point for the specified temperature shall be on the soldered part of the lead.

